# Specification of Thermoelectric Module TETC1-21908

## **Description**

The 219 couples, 55mm × 50mm size module is made of selected high performance ingot and fabricated by our unique "soft" processes to achieve superior cooling/heating performance. The module is able to run million thermal cycles in 70 °C temperature change range with less 3% degrading. It is good for the need of frequently cooling down and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

#### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance
- Sustain million thermal cycles with 70 °C temperature change range

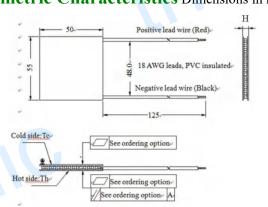
# **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

## **Performance Specification Sheet**

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Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	74 83		Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
$U_{max}(Voltage)$	28.9	31.1	Voltage applied to the module at DT <sub>max</sub>
$I_{max}(amps)$	8.4	8.4	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	154.2	168.9	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	2.6	2.87	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



# **Ordering Option**

			-
Suffix	Thickness	Flatness/	Lead wire length(mm)
Sullix	(mm)	Parallelism (mm)	Standard/Optional length
TF	0:3.4±0.1	0:0.1/0.1	125±1/Specify
TF	1:3.4±0.05	1:0.05/0.05	125±1/Specify

Eg. TF00: Thickness  $3.4 \pm 0.1$  (mm) and Flatness 0.1/0.1 (mm)

# **Manufacturing Options**

#### A. Solder:

**B. Sealant:** 

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

#### C. Ceramics:

D. Ceramics Surface Options:

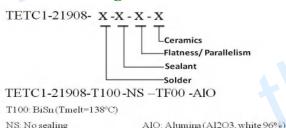
1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

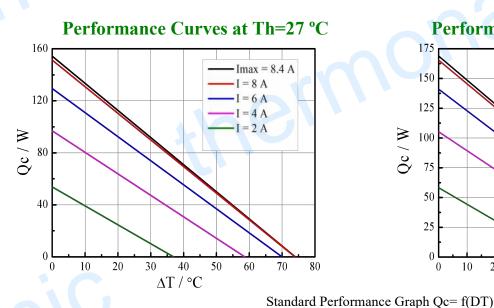
# Naming for the Module

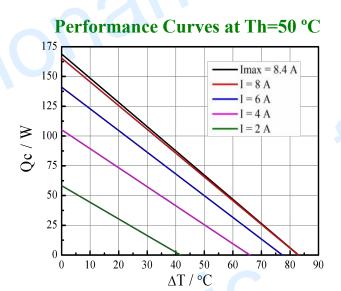


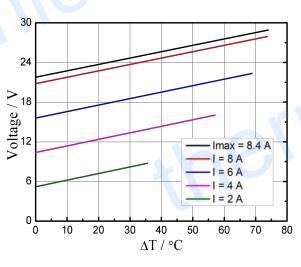
## **Operation Cautions**

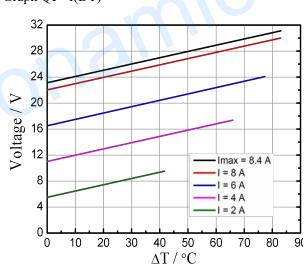
- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

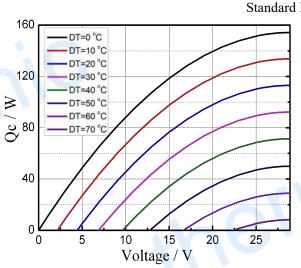
#### **Performance Curve**

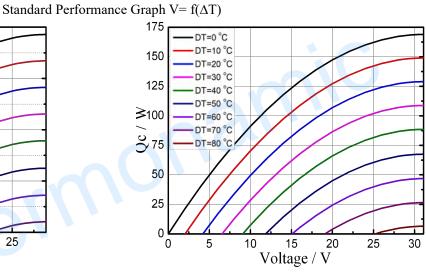








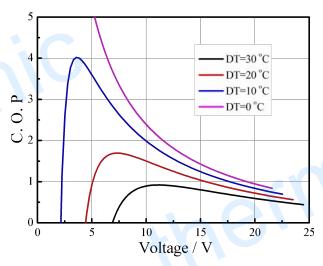


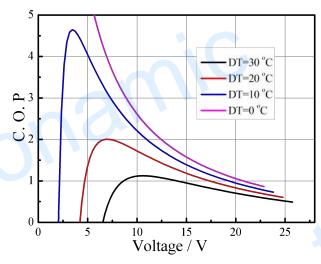


Standard Performance Graph Qc = f(V)

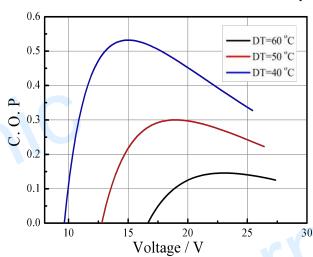


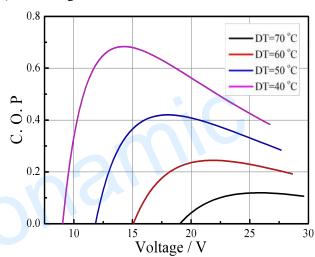
## Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C



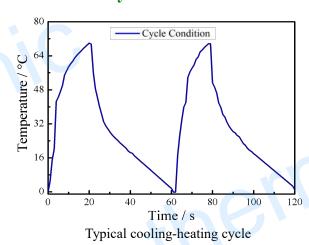


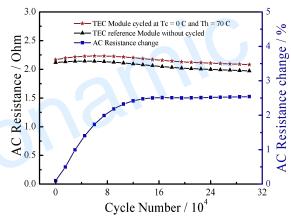
Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

A typical 127 couples module is fabricated by the unique "soft" process and has demonstrated that it only has 2.5% degrading after 300,000 thermal cycling. The below graphic shows that in beginning 120,000 cycles, it degrade about 2.5%, and then go on stable with very tiny degrading in further 180,000 thermal cycles. It is derived out that the modules can go over million thermal cycles.

## TEC Thermal Cycle Lifetime Test On TETC1-12706-74





The Chart for AC Resistance and AC Resistance Changes

vs Cycle Number